

ABSTRACT

A board-shaped thermal conductor base board (3) is arranged on the bottom surface of a power module (1).
5 Substrates (4) and (5) are arranged on the top surface of the thermal conductor base board (3), and semiconductor elements (6) and (7) are respectively arranged on the top surfaces of the substrates (4) and (5). The semiconductor elements (6, 7) are surrounded
10 by a resinous case (2). A source electrode (13) is attached above and apart from the semiconductor elements (6, 7) by using the resinous case (2). The connection between the source electrode (13) and the sources of the semiconductor elements (7) are connected by wire
15 bonding.